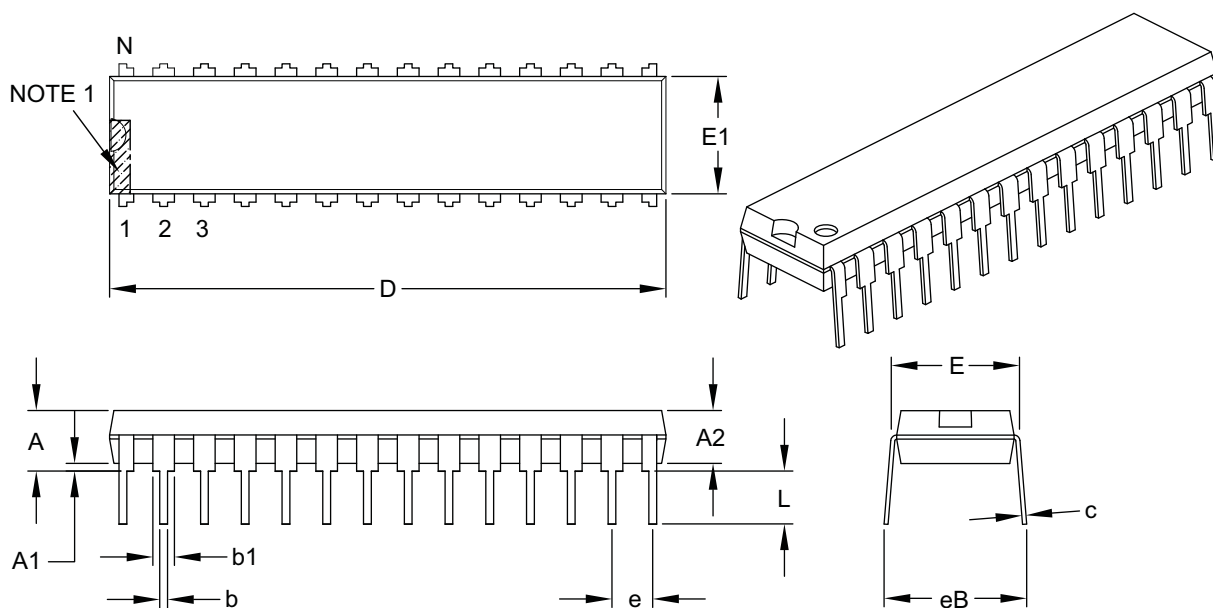


28-Lead Skinny Plastic Dual In-Line (PJ) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	INCHES		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		28		
Pitch	e		.100 BSC		
Top to Seating Plane	A		–	–	.200
Molded Package Thickness	A2		.120	.135	.150
Base to Seating Plane	A1		.015	–	–
Shoulder to Shoulder Width	E		.290	.310	.335
Molded Package Width	E1		.240	.285	.295
Overall Length	D		1.345	1.365	1.400
Tip to Seating Plane	L		.110	.130	.150
Lead Thickness	c		.008	.010	.015
Upper Lead Width	b1		.040	.050	.070
Lower Lead Width	b		.014	.018	.022
Overall Row Spacing §	eB		–	–	.430

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B